

SOT649A

leadless surface mounted package; plastic cap; 22 terminations

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	QMAN22
Package type industry code	QMAN22
Package style descriptive code	QMAN (quad microelectronic assembly; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-3-2006

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		11.95	-	12.25	12.55	mm
E	package width		9.5	-	9.8	10.1	mm
A	seated height		1.7	-	1.8	1.9	mm
n ₂	actual quantity of termination		-	-	22	-	



2. Package outline

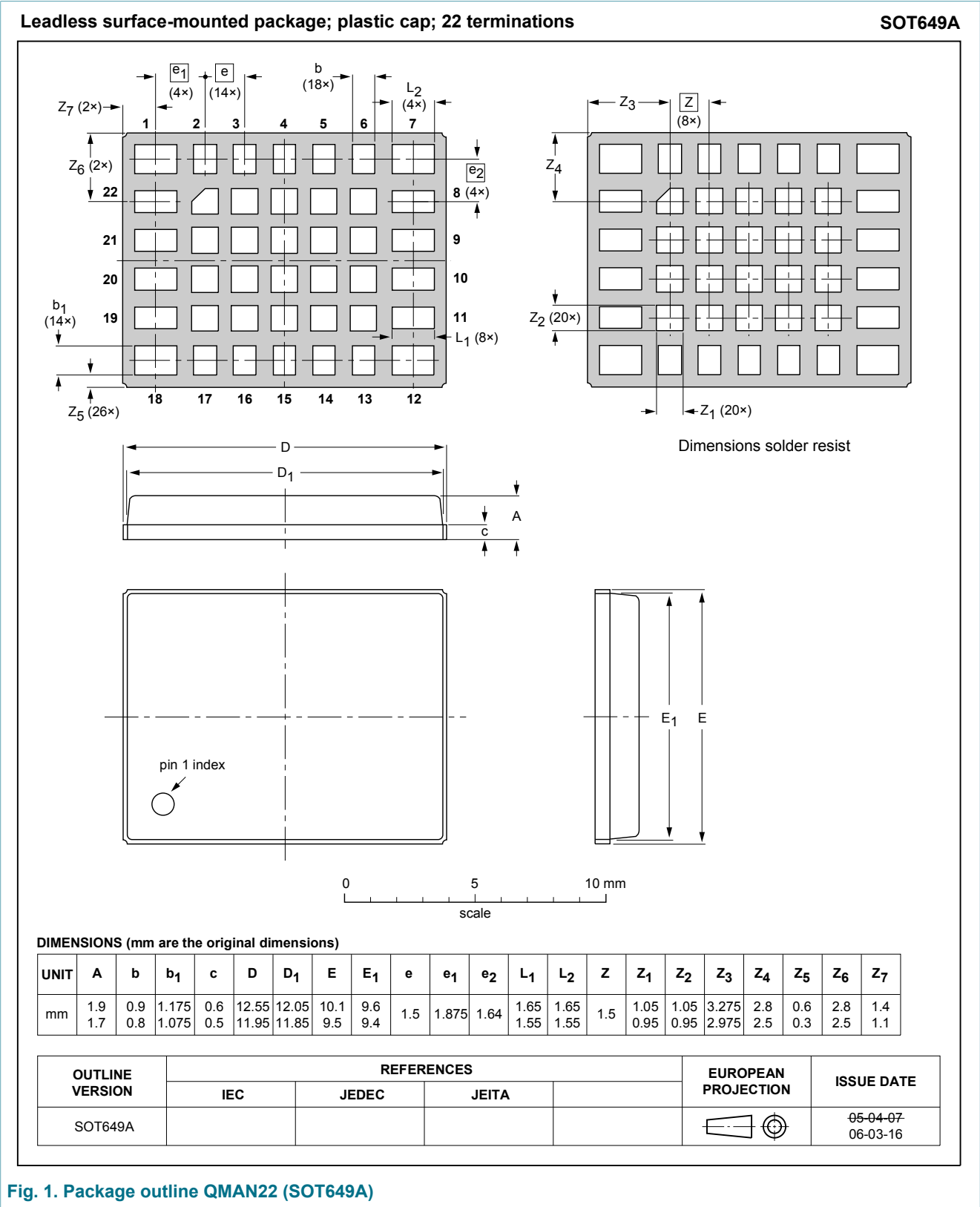
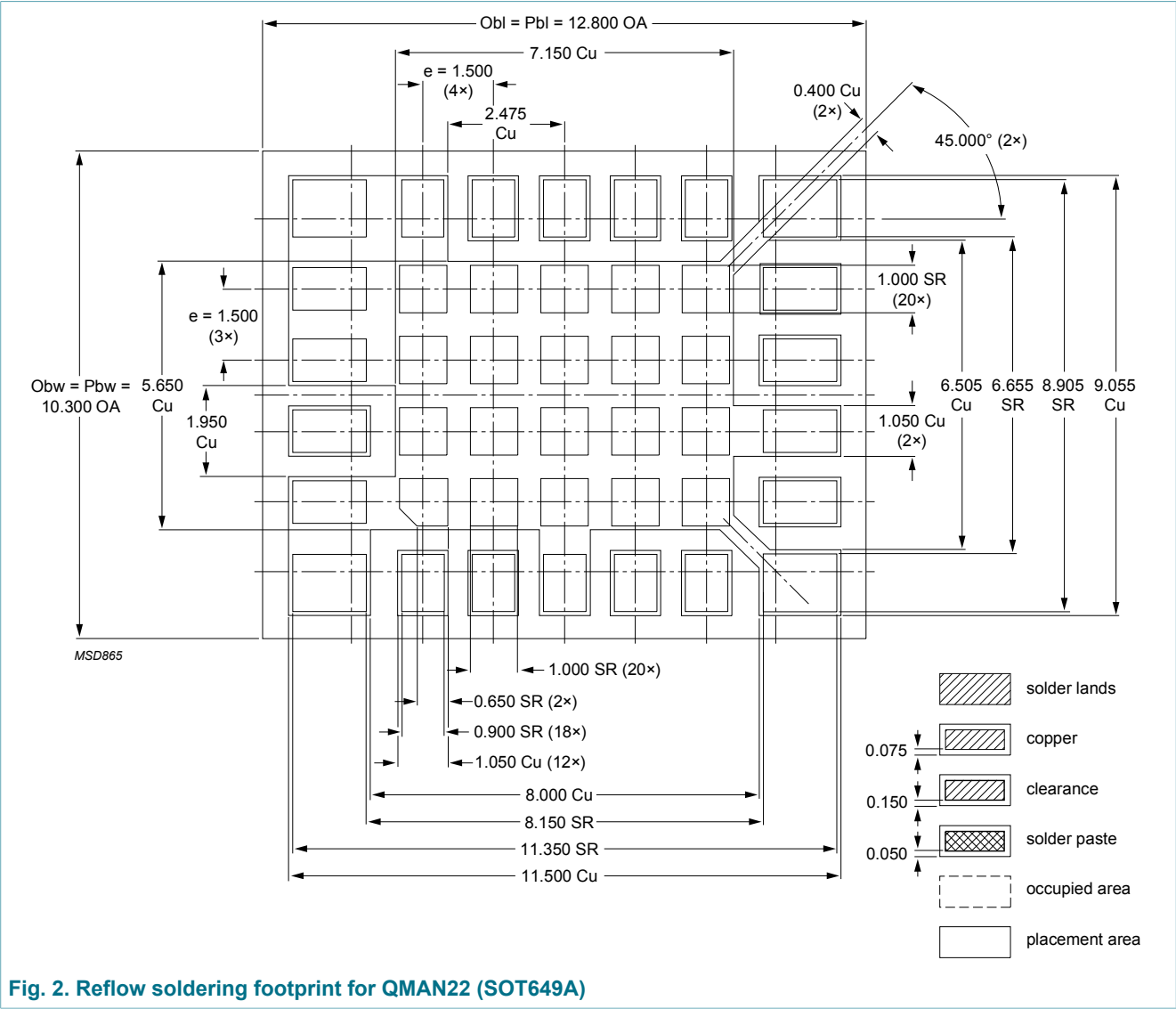


Fig. 1. Package outline QMAN22 (SOT649A)

3. Soldering



4. Legal information

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